



IEC 62631-3-1

HOSTAFORM® C 13021 LS 10/1570

HOSTAFORM®

POM copolymer

Easy flowing Injection molding type for precision molded parts and thin-walled molded parts with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. With UV Additives and a high amount of carbon black . Ranges of applications: automotive engineering, especially out door applications

Product information

Product information			
Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature	190		ISO 1133
Load Moulding shrinkage, parallel Moulding shrinkage, normal	2.16 2.0 1.8	%	ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, -30°C Charpy notched impact strength, -30°C Ball indentation hardness, H 358/30 Poisson's ratio [C]: Calculated	9 25 2800 2500 1300 200 200 6.5	MPa % % MPa MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 2039-1
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel	166 106 110		ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Thermal conductivity of melt Specific heat capacity of melt		W/(m K) J/(kg K)	ISO 22007-2 ISO 22007-4
Electrical properties			
Relative permittivity, 100Hz Relative permittivity, 1MHz Dissipation factor, 100Hz Dissipation factor, 1MHz		E-4 E-4	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1

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1E12 Ohm.m

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Volume resistivity





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Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent

Special characteristics U.V. stabilised or stable to weather

Additional information

Processing Notes Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

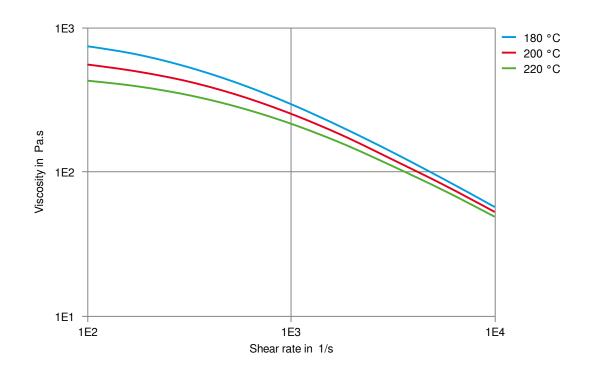
The product can then be stored in standard conditions until processed.

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Viscosity-shear rate

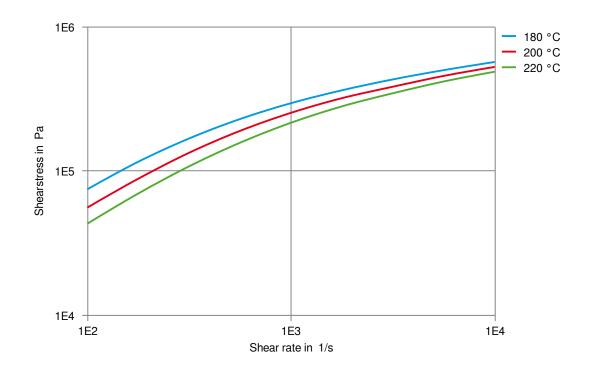


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Shearstress-shear rate

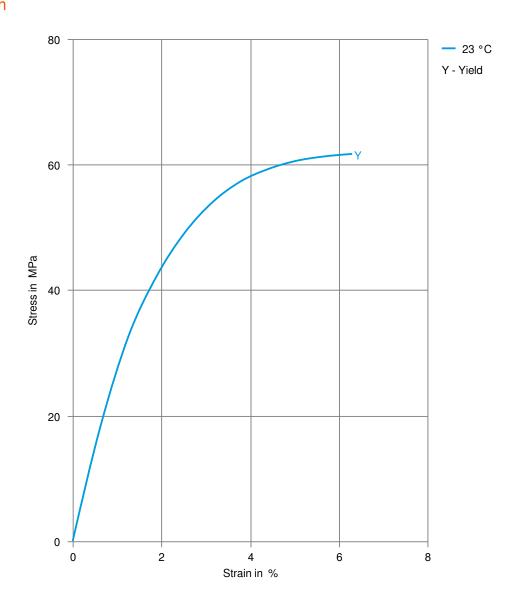


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Stress-strain

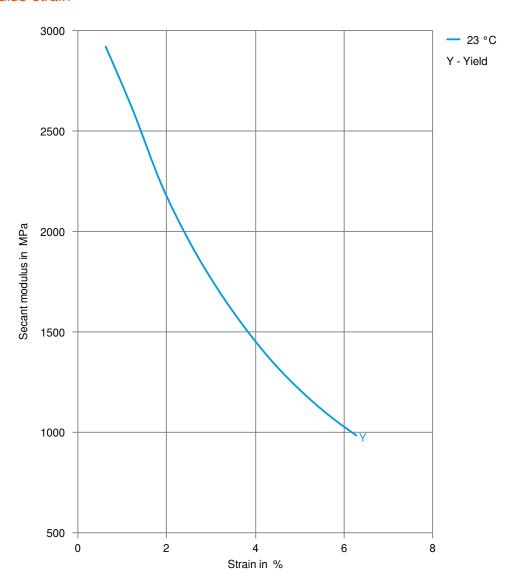


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Secant modulus-strain



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